**Product data sheet** 

## 1. General description

High voltage, high speed, planar passivated NPN power switching transistor in a SOT186A (TO220F) "full pack" plastic package.

### 2. Features and benefits

- Fast switching
- · Isolated package
- · Very high voltage capability
- · Very low switching and conduction losses

# 3. Applications

- DC-to-DC converters
- · High frequency electronic lighting ballasts
- Inverters
- Motor control systems

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>CM</sub>	peak collector current	Fig. 1; Fig. 2; Fig. 3	-	-	10	Α
P <sub>tot</sub>	total power dissipation	T <sub>h</sub> ≤ 25 °C; <u>Fig. 4</u>	-	-	32	W
V <sub>CESM</sub>	collector-emitter peak voltage	V <sub>BE</sub> = 0 V	-	-	1000	V
Static characte	eristics					
h <sub>FE</sub>	DC current gain	$I_C$ = 5 mA; $V_{CE}$ = 5 V; $T_h$ = 25 °C; Fig. 11	10	22	35	
		$I_C$ = 500 mA; $V_{CE}$ = 5 V; $T_h$ = 25 °C; Fig. 11	14	25	35	

# **5. Pinning information**

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	В	base	mb	С
2	С	collector		В
3	E	emitter		
mb	n.c.	mounting base; isolated	1 2 3 TO-220F (SOT186A)	Ë sym123

# 6. Ordering information

**Table 3. Ordering information** 

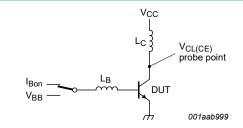
Type number	Package	kage				
	Name	Description	Version			
BUJ303AX	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A			

# 7. Limiting values

## **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CESM</sub>	collector-emitter peak voltage	V <sub>BE</sub> = 0 V	-	1000	V
$V_{CEO}$	collector-emitter voltage	I <sub>B</sub> = 0 A	-	500	V
I <sub>C</sub>	collector current	Fig. 1; Fig. 2; Fig. 3	-	5	Α
I <sub>CM</sub>	peak collector current		-	10	Α
$I_B$	base current	DC	-	2	Α
I <sub>BM</sub>	peak base current		-	4	Α
P <sub>tot</sub>	total power dissipation	T <sub>h</sub> ≤ 25 °C; <u>Fig. 4</u>	-	32	W
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		-	150	°C



$$\begin{split} &V_{CL(CE)} \leq 1000 \text{ V; } V_{CC} = 150 \text{ V; } V_{BB} = \text{--} 5 \text{ V;} \\ &L_{B} = 1 \text{ } \mu\text{H; } L_{C} = 200 \text{ } \mu\text{H} \end{split}$$

Fig. 1. Test circuit for reverse bias safe operating area

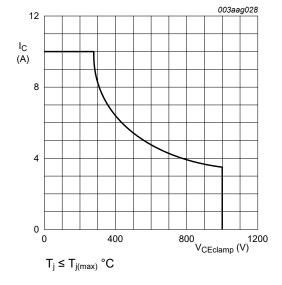
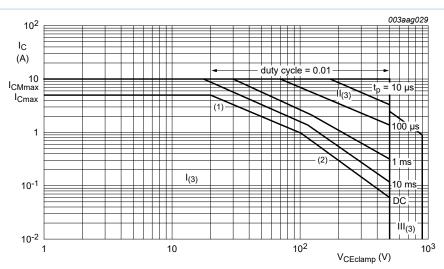


Fig. 2. Reverse bias safe operating area

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- (1)  $P_{tot}$  maximum and  $P_{tot}$  peak maximum lines. (2) Second breakdown limits.
- (3) I = Region of permissible DC operation.
  - II = Extension for repetitive pulse operation.
  - III = Extension during turn-on in single transistor converters provided that  $R_{BE} \le 100 \Omega$  and  $t_p \le 0.6 \mu s$ .

Fig. 3. Forward bias safe operating area for T<sub>mb</sub> ≤ 25 °C

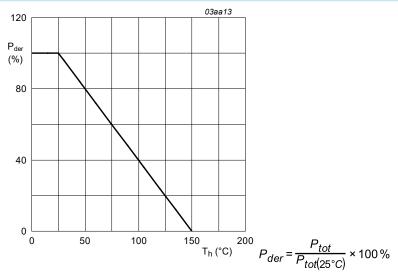


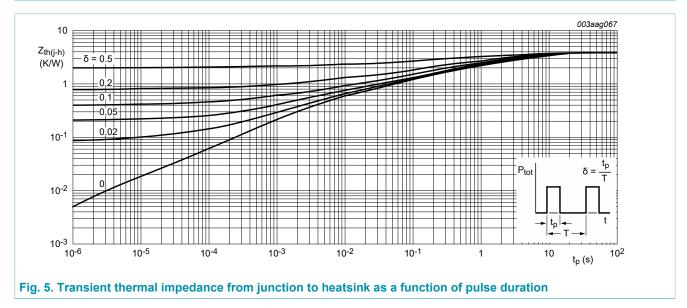
Fig. 4. Normalized total power dissipation as a function of heatsink temperature

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### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to heatsink	with heatsink compound; Fig. 5	-	-	3.95	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



### 9. Isolation characteristics

### **Table 6. Isolation characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; T <sub>h</sub> = 25 °C; from all terminals to external heatsink; clean and dust free	-	-	2500	V
C <sub>isol</sub>	isolation capacitance	from collector to external heatsink; f = 1 MHz; T <sub>h</sub> = 25 °C	-	10	-	pF

## 10. Characteristics

#### Table 7. Characteristics

	aracteristics Parameter	Conditions	Min	Tyre	Mov	Unit
Symbol	Parameter	Conditions	IVIIII	Тур	Max	Unit
Static char	acteristics					
I <sub>CES</sub>	collector-emitter cut-off current (base shorted)	V <sub>BE</sub> = 0 V; V <sub>CE</sub> = 1000 V; Measured with half-sine wave voltage (curve tracer)	-	-	2	mA mA
I <sub>CBO</sub>	collector-base cut-off current (emitter open)	V <sub>CB</sub> = 1000 V; I <sub>E</sub> = 0 A; T <sub>h</sub> = 25 °C; Measured with half-sine wave voltage (curve tracer)	-	-	1	mA
I <sub>CEO</sub>	collector-emitter cut-off current (base open)	V <sub>CE</sub> = 500 V; I <sub>B</sub> = 0 A; T <sub>h</sub> = 25 °C; Measured with half-sine wave voltage (curve tracer)	-	-	0.1	mA
I <sub>EBO</sub>	emitter-base cut-off current (collector open)	$V_{EB} = 9 \text{ V}; I_{C} = 0 \text{ A}; T_{h} = 25 \text{ °C}$	-	-	0.1	mA
V <sub>CEOsus</sub>	collector-emitter sustaining voltage (base open)	$I_B = 0 \text{ A}; I_C = 100 \text{ mA}; L_C = 25 \text{ mH};$ $T_h = 25 ^{\circ}\text{C}; \frac{\text{Fig. 6}}{\text{Fig. 7}}; \frac{7}{\text{Fig. 7}}$	500	-	-	V
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 3 \text{ A}; I_B = 0.6 \text{ A}; T_h = 25 °C; Fig. 8; Fig. 9$	-	0.35	1.5	V
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = 3 \text{ A}; I_B = 0.6 \text{ A}; T_h = 25 °C; Fig. 10$	-	1.01	1.3	V
h <sub>FE</sub>	DC current gain	$I_C = 5 \text{ mA}; V_{CE} = 5 \text{ V}; T_h = 25 ^{\circ}\text{C};$ Fig. 11	10	22	35	
		$I_C$ = 500 mA; $V_{CE}$ = 5 V; $T_h$ = 25 °C; Fig. 11	14	25	35	
h <sub>FEsat</sub>	DC saturation current gain	$I_C = 2.5 \text{ A}; V_{CE} = 5 \text{ V}; T_h = 25 ^{\circ}\text{C};$ Fig. 11	10	13.5	17	
		I <sub>C</sub> = 3 A; V <sub>CE</sub> = 5 V; T <sub>h</sub> = 25 °C; <u>Fig. 11</u>	-	11	-	
Dynamic cl	haracteristics (switching tir	mes - resistive load)				
t <sub>s</sub>	turn-off delay time	I <sub>C</sub> = 2.5 A; I <sub>Bon</sub> = 0.5 A; I <sub>Boff</sub> = -0.5 A;	-	3.3	4	μs
t <sub>f</sub>	fall time	$R_L = 75 \Omega$ ; $T_h = 25 °C$ ; Fig. 12; Fig. 13	_	0.33	0.45	μs
•	haracteristics (switching tir	nes - inductive load)				•
t <sub>s</sub>	turn-off delay time	$I_C = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; V_{BB} = -5 \text{ V};$ $L_B = 1 \mu\text{H}; T_h = 25 \text{ °C}; Fig. 14; Fig. 15$	-	1.4	1.6	μs
		I <sub>C</sub> = 2.5 A; I <sub>Bon</sub> = 0.5 A; V <sub>BB</sub> = -5 V; L <sub>B</sub> = 1 μH; T <sub>h</sub> = 100 °C; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	1.7	1.9	μs
t <sub>r</sub>	rise time	I <sub>C</sub> = 2.5 A; I <sub>Bon</sub> = 0.5 A; V <sub>BB</sub> = -5 V; L <sub>B</sub> = 1 μH; T <sub>h</sub> = 25 °C; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	145	160	ns
		I <sub>C</sub> = 2.5 A; I <sub>Bon</sub> = 0.5 A; V <sub>BB</sub> = -5 V; L <sub>B</sub> = 1 μH; T <sub>h</sub> = 100 °C; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	160	200	ns

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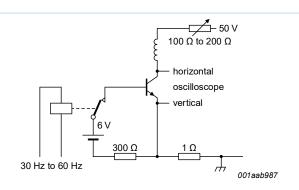


Fig. 6. Test circuit for collector-emitter sustaining voltage

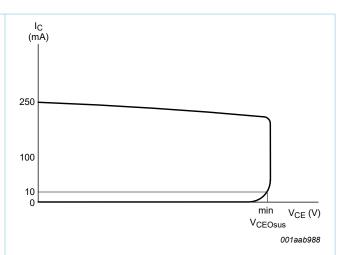


Fig. 7. Oscilloscope display for collector-emitter sustaining voltage test waveform

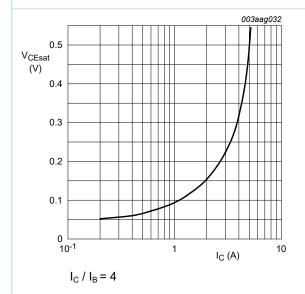


Fig. 8. Collector-emitter saturation voltage as a function of collector current; typical values

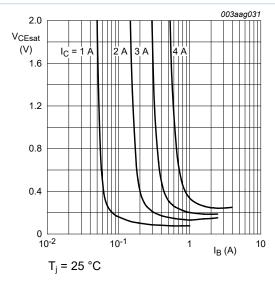


Fig. 9. Collector-emitter saturation voltage as a function of base current; typical values

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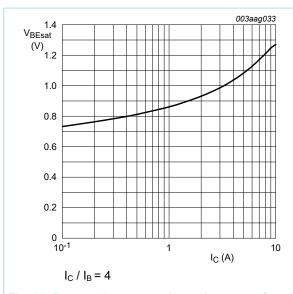


Fig. 10. Base-emitter saturation voltage as a function of collector current; typical values

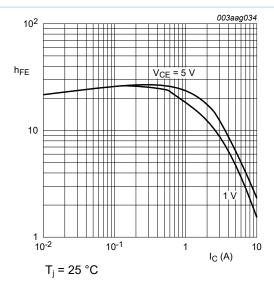
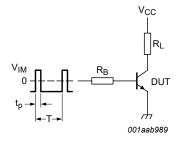


Fig. 11. DC current gain as a function of collector current; typical values



 $V_{IM}$ = - 6 to + 8 V;  $V_{CC}$  = 250 V;  $t_p$  = 20 us;  $\delta$  =  $t_p$ /T = 0.01  $R_B$  and  $R_L$  calculated from  $I_{Con}$  and  $I_{Bon}$  requirements.

Fig. 12. Test circuit for resistive load switching

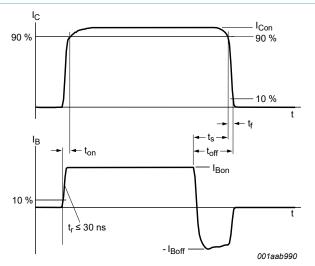
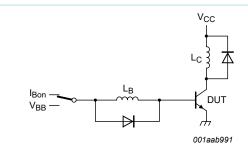


Fig. 13. Switching times waveforms for resistive load

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 $V_{CC}$  = 300 V;  $V_{BB}$  = - 5 V;  $L_{C}$  = 200  $\mu H;$   $L_{B}$  = 1  $\mu H$ 

Fig. 14. Test circuit for inductive load switching

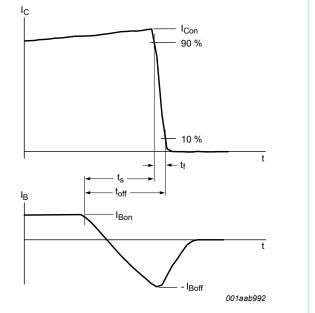


Fig. 15. Switching times waveforms for inductive load

# 11. Package outline

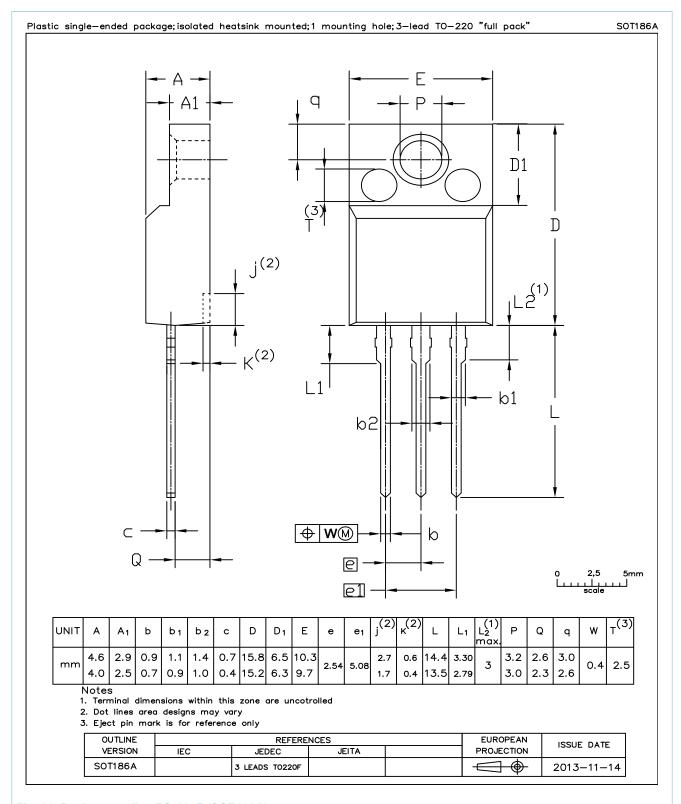


Fig. 16. Package outline TO-220F (SOT186A)

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# 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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# **BUJ303AX**

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